

Product Information

Ultra Soft Impact Nozzle

*Create a puddle
in one second
with a uniform
arrival pressure
of 0.005 psi.*

The Ultra Low Impact develop nozzle from S³ has been designed to provide a very high rate of flow of liquid to the wafer while virtually eliminating impact or impingement of the arriving fluid. As is well understood among lithographers, there are many contributors to develop rate including chemical corrosion and mechanical erosion aspects. Mechanical erosion is not controlled by the chemistry but by the arrival pressure of the develop fluid.

The chemical aspects of develop are:

- Concentration of developer
- Uniformity of dispense
- Uniformity of rinse
- Time of rinse
- Time of dispense
- Temperature of developer

The mechanical aspects (erosion) of the develop process are:

- Arrival rate of dispense
- Pressure of dispense
- Uniformity of dispense

The time of dispense must be short but the impact must be very low. The new system from S³ incorporates a combination of multiple nozzles, a plenum and a breaker plate as a means to achieve a very high rate of puddle build, combined with a very low arrival pressure. The new nozzle permits building a develop puddle in one second at an arrival pressure of 0.005 psi. Likewise, rinse can be accomplished at the same rate and through the same nozzle.

*Service Support Specialties,
Inc.*

PO Box 365
Montville, NJ 07045-0365

Phone: 973-263-0640

Fax: 973-263-8888

Email: info@s-cubed.com

Website: WWW.S-CUBED.COM

For more information please contact the factory.

